



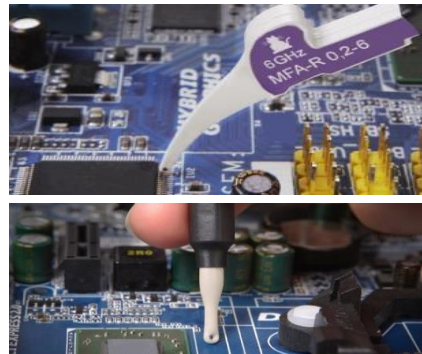
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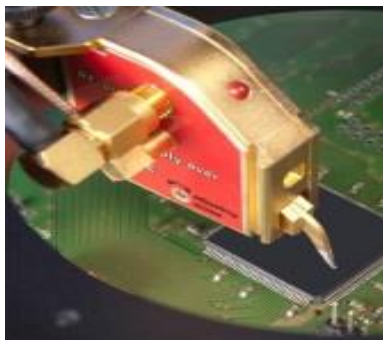
Emission

Immunity

PCB



IC





Understanding Physics behind Emissions

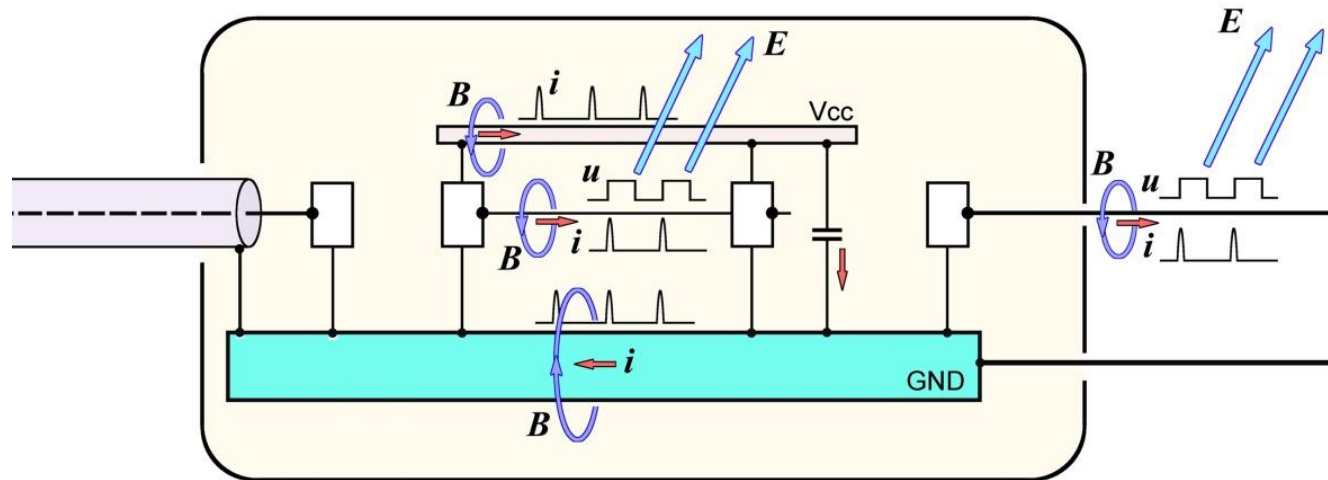
Interactions Between PCB's and Their Surroundings

Speaker: Dipl. Ing. Jörg Hacker

- 1 Disturbance Emission Sources
- 2 Magnetic and Electric Coupling Effects
- 3 Pre-Compliance Measurement Methods
- 4 Practical Examples

ICs are the sources of disturbance emission:

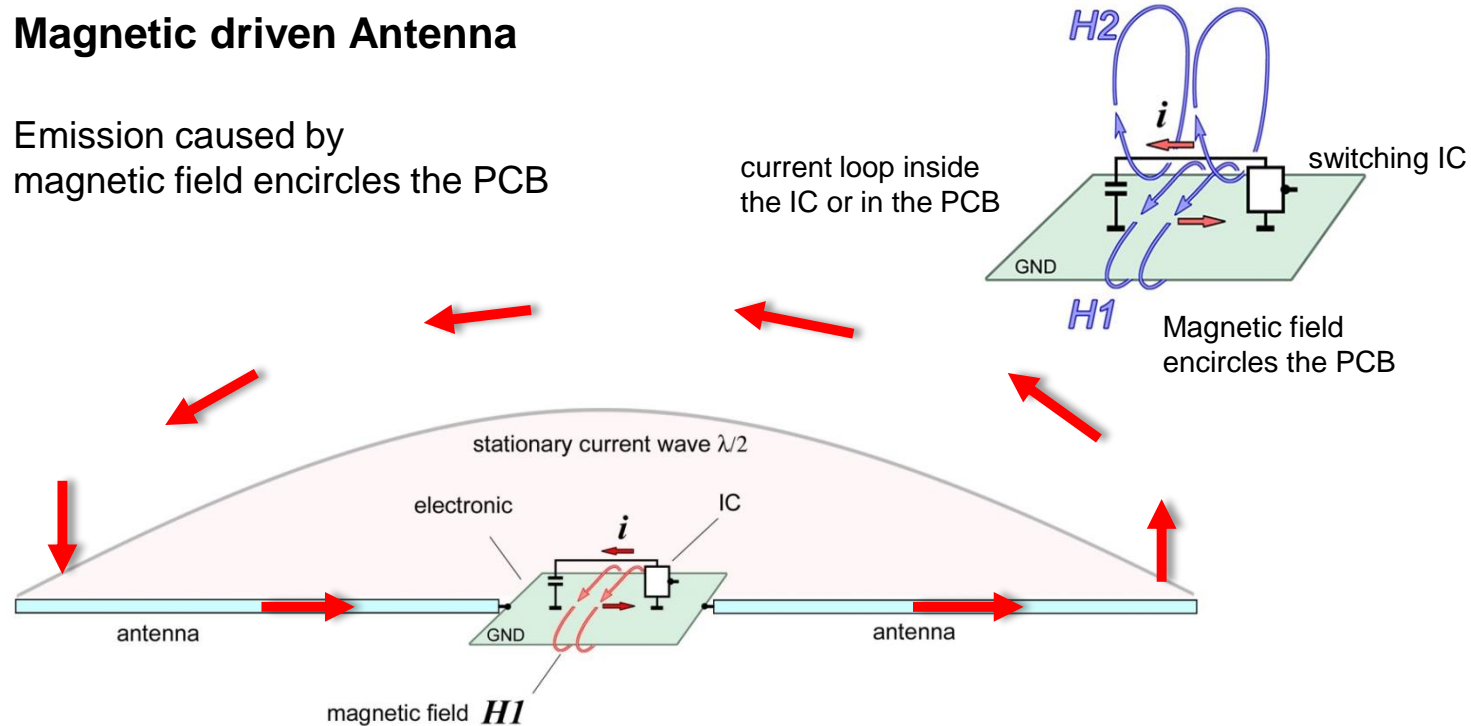
- ICs operate with clocked signals.
- The signal's current and voltage create emission via magnetic and electric near-field coupling into an antenna.



Most sources are very small in relation to the wavelength => an antenna is needed.

Magnetic driven Antenna

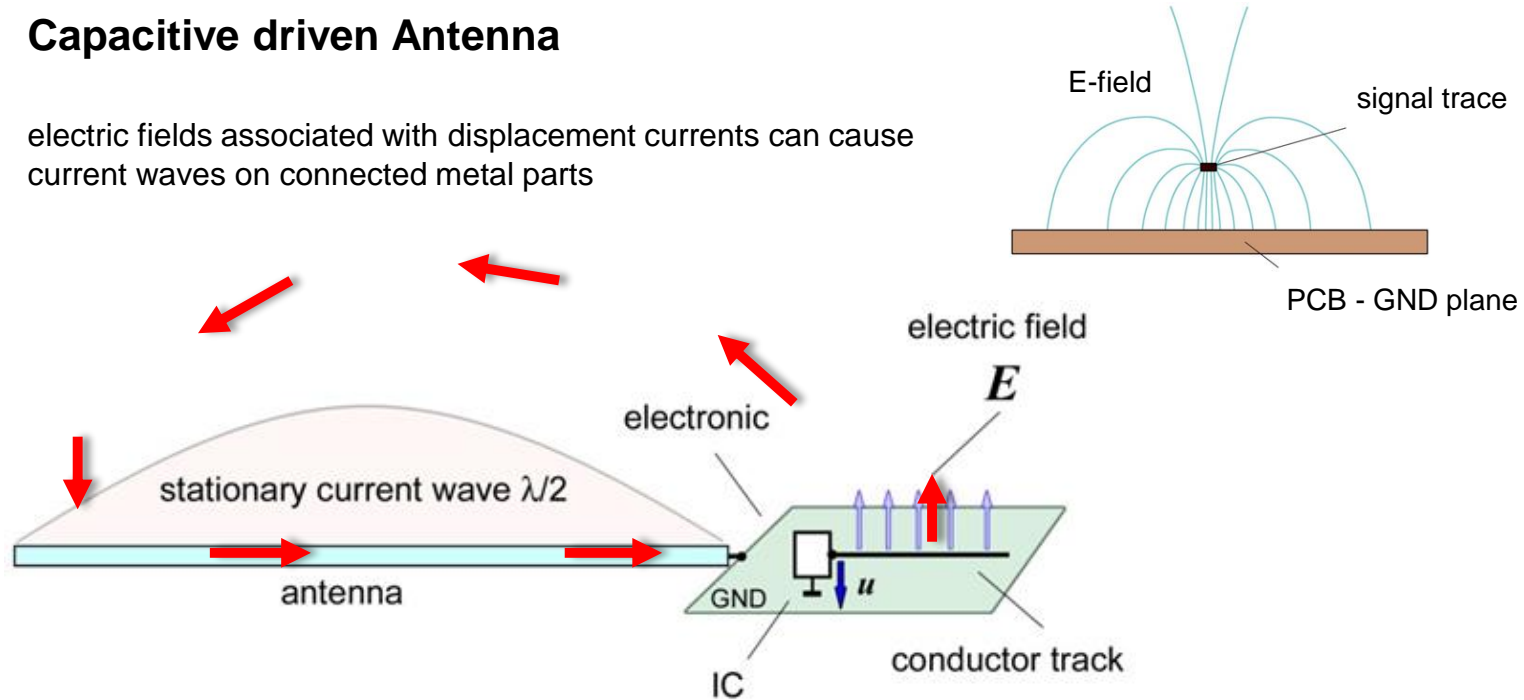
Emission caused by
magnetic field encircles the PCB



Radiation depends on the position of the near-field source in the antenna!

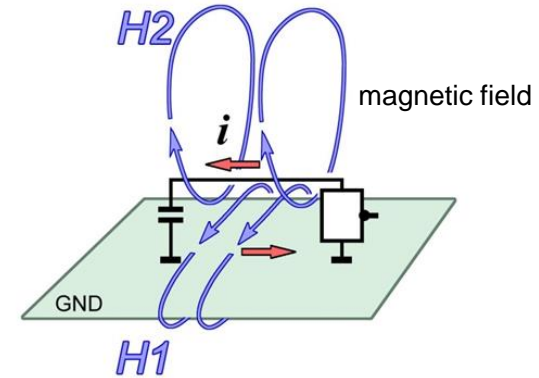
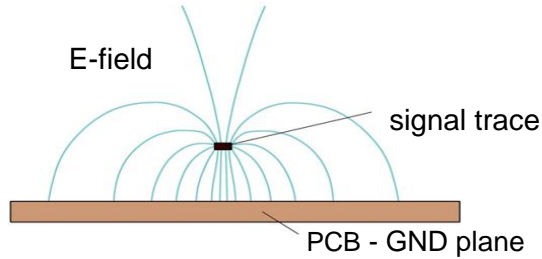
Capacitive driven Antenna

electric fields associated with displacement currents can cause current waves on connected metal parts



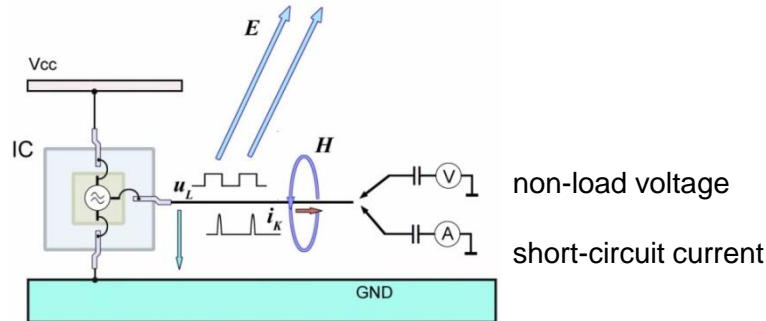
Radiation depends on the position of the near-field source in the antenna!

Comparison of electric and magnetic field source

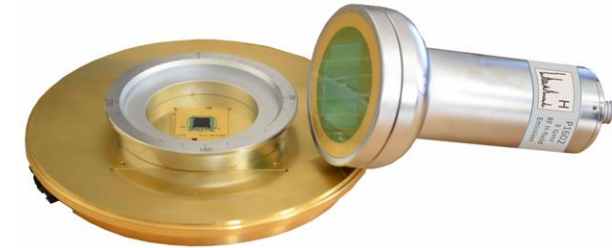


Determining an ICs relevant emission parameters by:

- Measuring voltage and current at the IC pin (non load and short-circuit measurements)

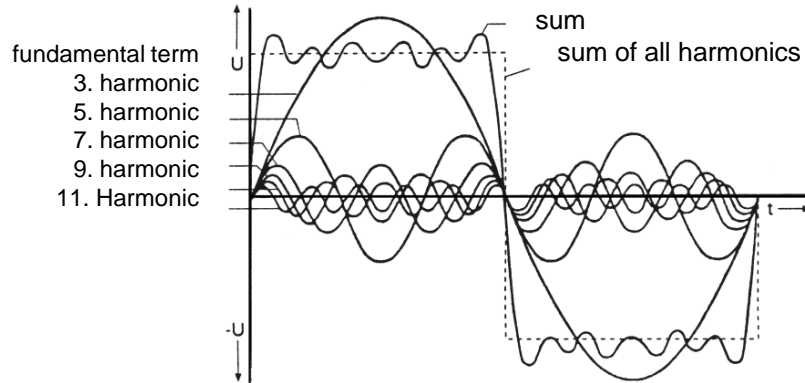


- Measuring magnetic and electric field above the IC

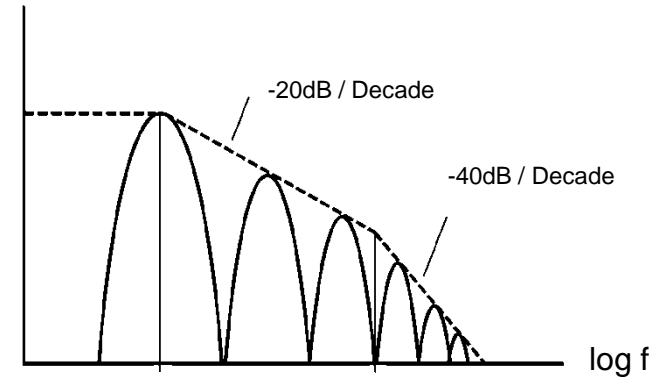


Relationship between time domain and frequency domain:

Example: digital signal (50% high, 50% low, no DC component):

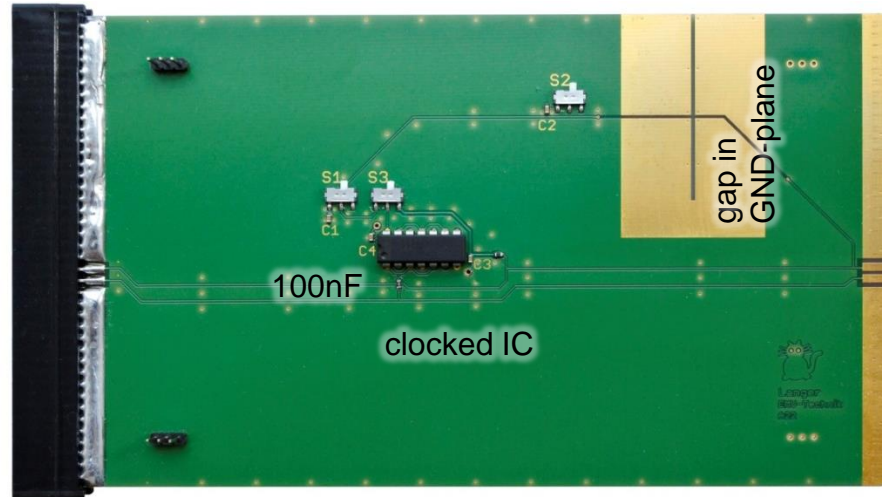


$$u(t) = \frac{4}{\pi} \left(\sin t + \frac{1}{3} \sin(3t) + \frac{1}{5} \sin(5t) + \frac{1}{7} \sin(7t) + \dots \right)$$

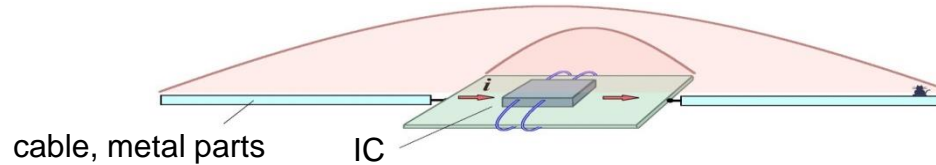


Sample: magnetic field on a PCB with clocked IC

- four-layer PCB
- closed GND-plane



- power supply
- clock signal

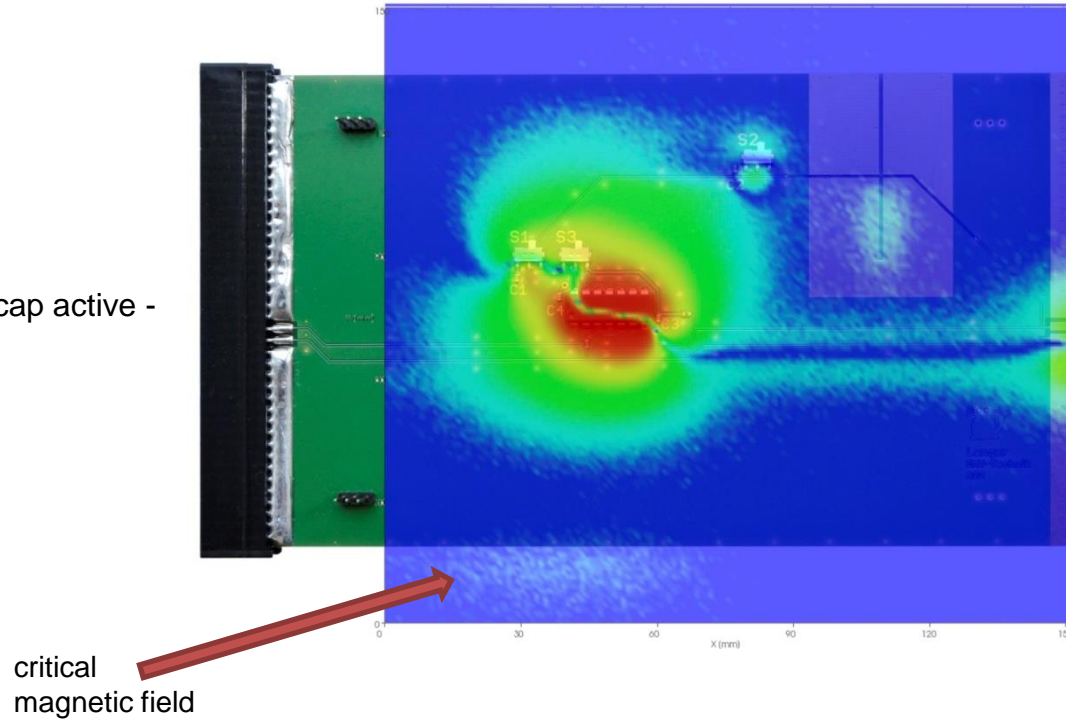


Magnetic Coupling Effects



Sample: magnetic field on a PCB with clocked IC

- decoupling cap active -



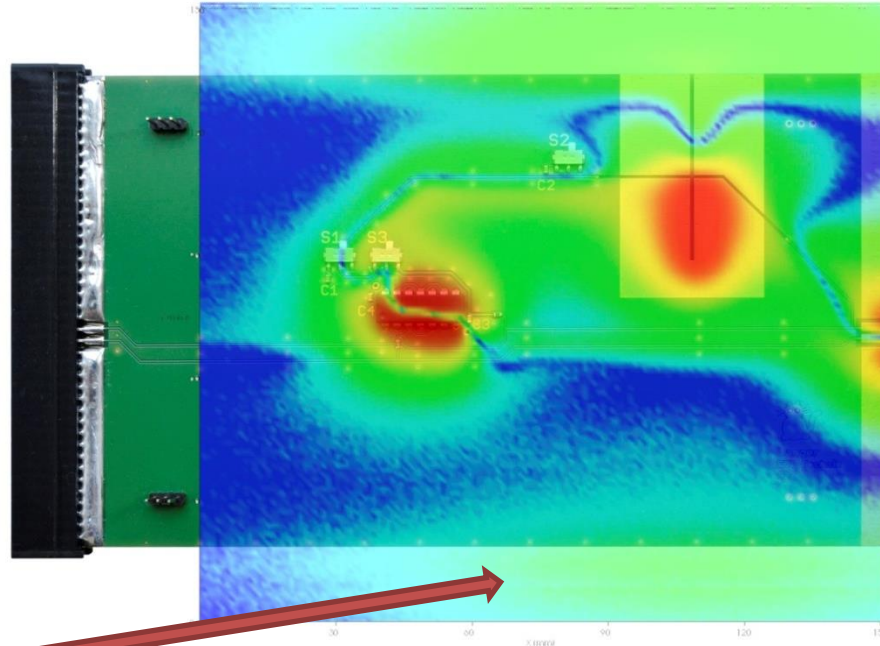
Magnetic field measurement
with scanner and probe
ICR H500

Magnetic Coupling Effects



Sample: magnetic field on a PCB with clocked IC

- without decoupling cap -



critical
magnetic field

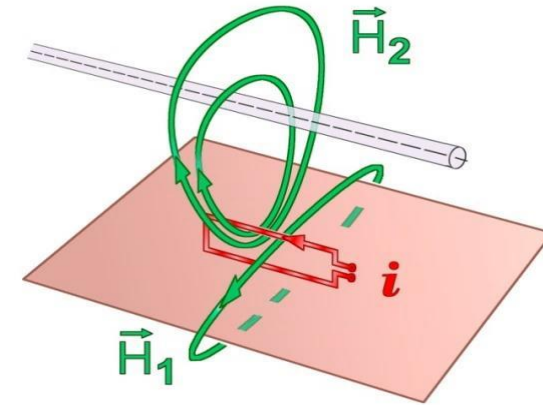
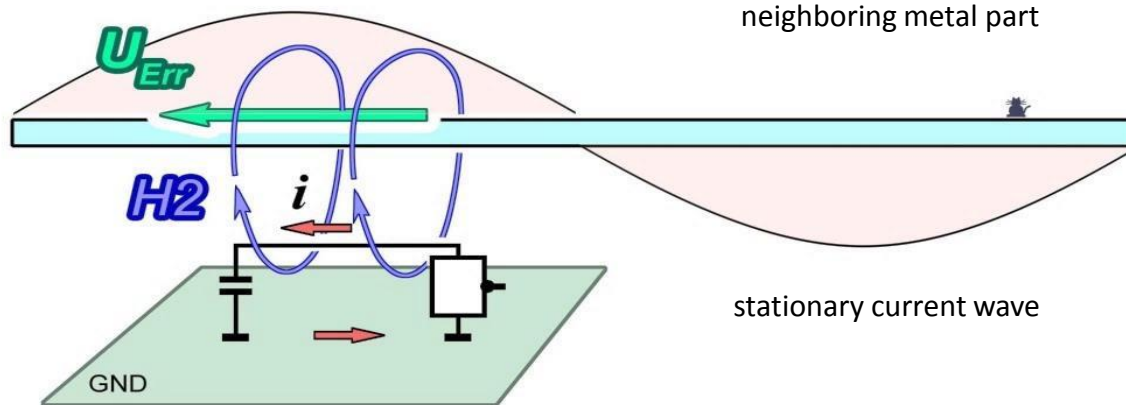


Magnetic field measurement
with scanner and probe
ICR H500

Various objects can function as an antenna:

The induction effect in neighboring metal parts causes radiation!

Beware! H_2 is often significantly bigger than H_1 !



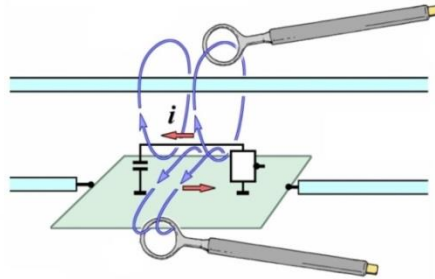
Emission depends on the position of the source!

Field measurement with near-field probes

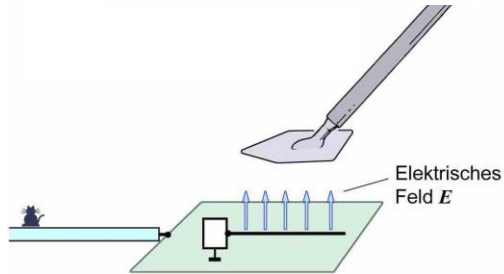
Two different measurement tasks:

- qualifying the emission effects
big (sensitive) probes
to use in a distance to the PCB

magnetic field:

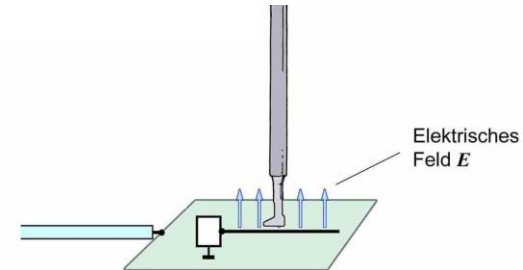
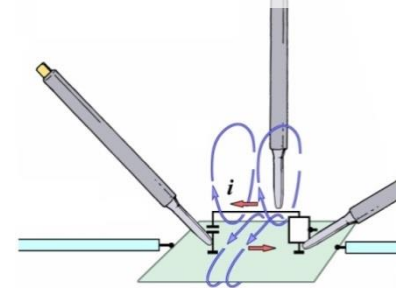


electric field:



- localizing the source

small probes for high accuracy
to use close to the components



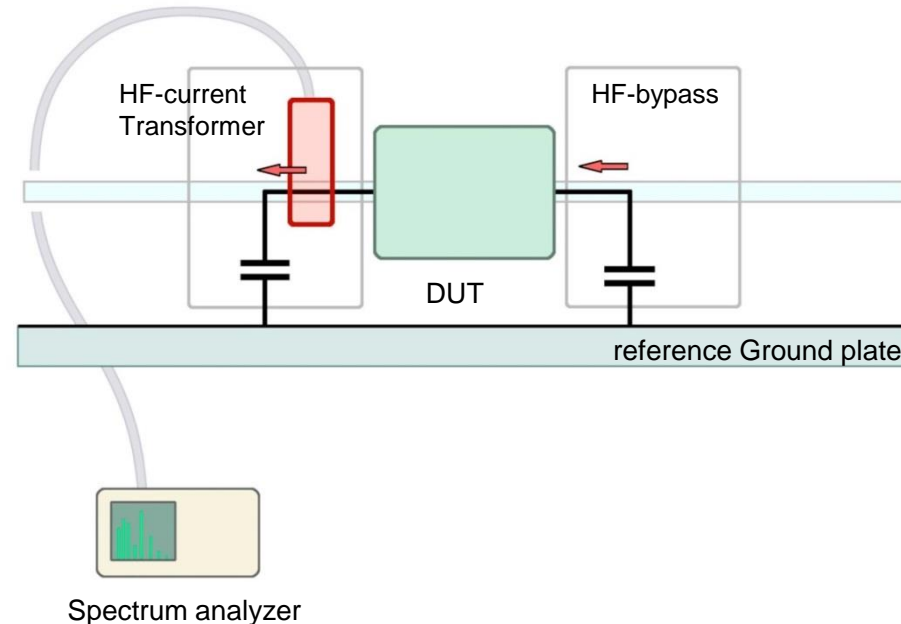
How emission measurements can be done on the developers desk?

Excitation currents are short-circuited through the reference Ground plate (capacitively) and measured with an HF-current transformer.

The current path should be shorter than half of the wavelength to prevent standing waves.

Measurement method characteristics:

- total device emission values not possible to measure
- applicable during the development stages only
- useful for quick valuation of modifications
- portable enough to use at the developer's desk

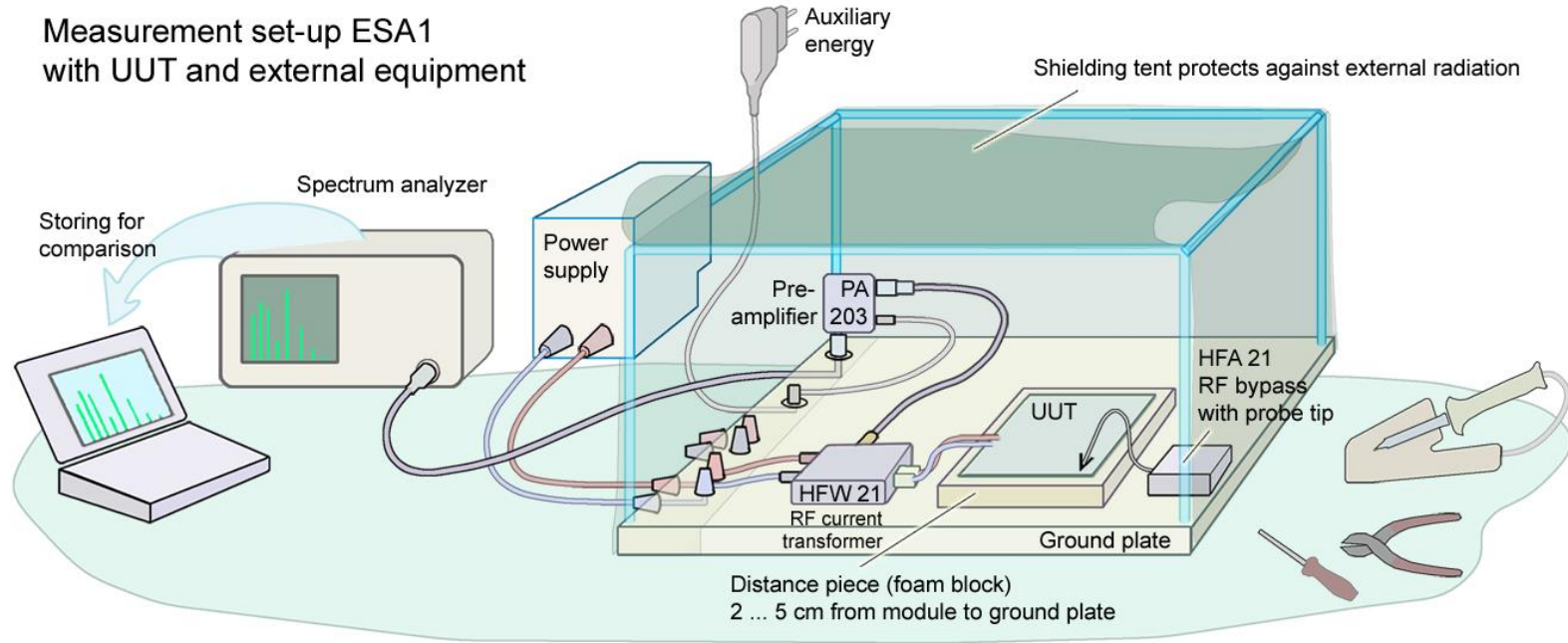


Pre-Compliance Measurement Methods

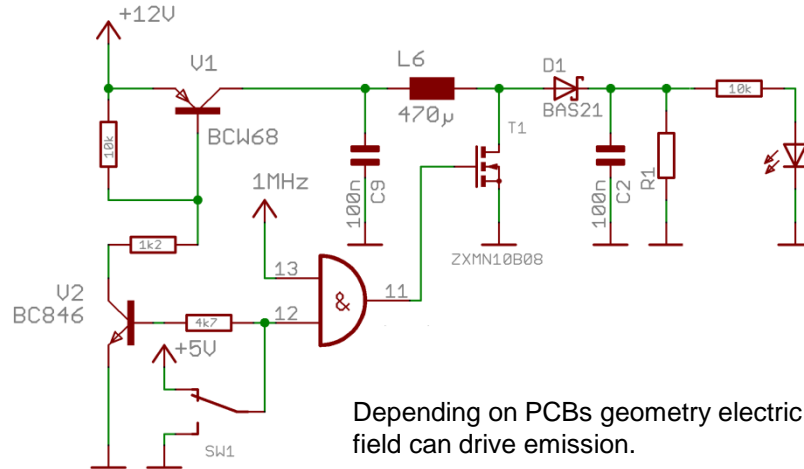


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Measurement set-up ESA1
with UUT and external equipment



Electric Field Source: Step-Up converter

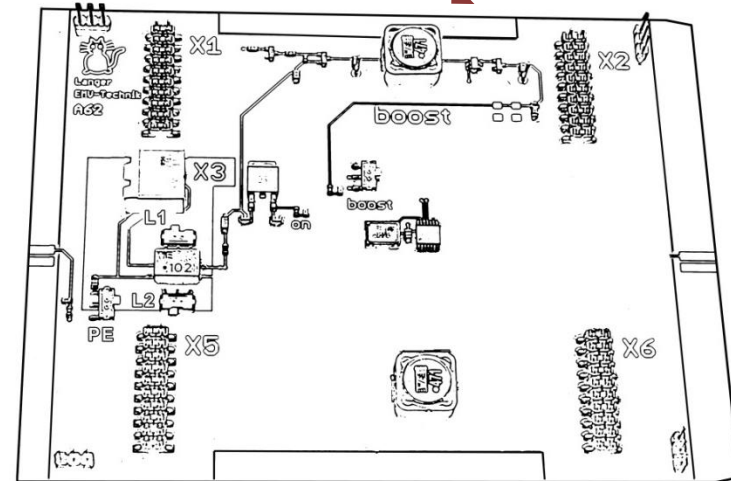


Depending on PCBs geometry electric or magnetic field can drive emission.

In this example the electric field generated by the boost converter coil determines the emission.

Test setup: ESA1

Boost converter coil



Electric Field Source: Step-Up converter

converter coil (high element) acts as an electric field source:

Maybe shielding is needed!

Resonance effects can occur!
capacitance between both PCBs and inductance of the
connector = resonant circuit

Problem-solving strategy:
significant reduction of the inductance by using
more connectors (or screws or contact springs)
in parallel

